We connect and protect

Interscale Flexible Heat Conductor (FHC), 20 mm

Power Utilities

Conductor block expands/contracts vertically to compensate for tolerance stack up and optimizes surface contact and pressure along the thermal path; eliminates the need for a thermal gap pad.

CERTIFICATIONS

RoHS COMPLIANT

FEATURES

- Designed for Intel, AMD, Via, Freescale, NVidia and Texas Instrument processors that employ a BGA socket
- Provides industry-leading conduction cooling performance, 10% improvement over current conduction cooling methods
- Patent pending conduction cooling solution for small form factor electronics
- Secured to PCB with thermally conductive adhesive tape
- Conductor block expands/contracts vertically to compensate for tolerance stack up and optimizes surface contact and pressure along the thermal path; eliminates the need for a thermal gap pad
- Compatible with Interscale C enclosures

SPECIFICATIONS

Table 1/1

Catalog Number	Type	Works With	Package Quantity	Depth	Width

24830-005	Heat Conductor	Cases	1	22 mm	22 mm

WARNING

nVent products shall be installed and used only as indicated in nVent's product instruction sheets and training materials. Instruction sheets are available at www.nvent.com and from your nVent customer service representative. Improper installation, misuse, misapplication or other failure to completely follow nVent's instructions and warnings may cause product malfunction, property damage, serious bodily injury and death and/or void your warranty.

Our powerful portfolio of brands:

CADDY ERICO HOFFMAN ILSCO SCHROFF TRACHTE

©2025 nVent. All nVent marks and logos are owned or licensed by nVent Services GmbH or its affiliates. All other trademarks are the property of their respective owners. nVent reserves the right to change specifications without notice.

This document is system-generated.